L Number	Hits	Search Text	DB	Time stamp
1	6	"6180995"	USPAT;	2004/09/07 07:02
			US-PGPUB;	2001, 02, 01
			EPO; JPO	
2	9	"6307247"	USPAT;	2004/09/07 07:03
		0307247	Ť	2004/03/07 07:03
	}		US-PGPUB;	
		"	EPO; JPO	
3	13	"6287979"	USPAT;	2004/09/07 07:03
			US-PGPUB;	
			EPO; JPO	
4	16	"4634494"	USPAT;	2004/09/07 07:03
			US-PGPUB;	
			EPO; JPO	
5	19	"5742091"	USPAT;	2004/09/07 07:03
			US-PGPUB;	
			EPO; JPO	
6	16	"6303423"	USPAT;	2004/09/07 07:03
			US-PGPUB;	
			EPO; JPO	
7	72	"6180995" "6307247" "6287979" "4634494"	USPAT;	2004/09/07 07:04
'	, -	"5742091" "6303423"	US-PGPUB;	2004/03/07/07.04
		5,12071 0303423	4	
8	39	inductor and (oxide adj layer) and	EPO; JPO USPAT;	2004/09/07 07:15
0	39		l ·	2004/09/07 07:15
		("low-k" adj dielectric)	US-PGPUB;	
10		/ dend	EPO; JPO	2004/20/2= 2= 3=
10	ا 3	(inductor and (oxide adj layer) and	USPAT;	2004/09/07 07:15
		("low-k" adj dielectric)) and (air adj	US-PGPUB;	
		gap)	EPO; JPO	
9	39		USPAT;	2004/09/07 07:06
		("low-k" adj dielectric)) and (method	US-PGPUB;	
		process)	EPO; JPO	
11	120	inductor and oxide and ("low-k" nearl	USPAT;	2004/09/07 07:15
		(insulation dielectric))	US-PGPUB;	
			EPO; JPO	
12	17	(inductor and oxide and ("low-k" nearl	USPAT;	2004/09/07 07:15
		(insulation dielectric))) and (air adj	US-PGPUB;	
		gap)	EPO; JPO	
13	o	inductor and (oxide with ("low-k" nearl	USPAT;	2004/09/07 07:17
		(insulation dielectric)) with (air adj	US-PGPUB;	
		gap))	EPO; JPO	
14	o	inductor and (oxide with "low-k" with	USPAT;	2004/09/07 07:18
		(air adj gap))	US-PGPUB;	2001,03,07,07.10
		(dir dd) gdp//	EPO; JPO	
15	0	inductor and (oxide near1 layer) and	USPAT;	2004/09/07 07:19
		("low-k" with (air adj gap))	I *	2004/09/07 07:19
		(IOW-K WICH (AIL AU) Gap/)	US-PGPUB;	
16	21	inductor and (oride moont lover) and	EPO; JPO	
16	31	inductor and (oxide near1 layer) and	USPAT;	2004/09/07 07:19
		(("low-k" dielectric) with (air adj gap))	US-PGPUB;	
1 1 7	_	CAREROS IIDEN	EPO; JPO	
17) o	6495903.URPN.	USPAT	2004/09/07 07:23
18	8	("5539241" "5831331" "6153489"	USPAT	2004/09/07 07:23
		"6180433" "6221727" "6242791"		
		"6274920" "6287931").PN.		
19	67	("6180995" "6307247" "6287979" "4634494"	USPAT;	2004/09/07 08:19
<u> </u>		"5742091" "6303423") not ((inductor and	US-PGPUB;	[
]		(oxide adj layer) and ("low-k" adj	EPO; JPO	
		dielectric)) and (method process)) not		
	İ	((inductor and oxide and ("low-k" near1		
		(insulation dielectric))) and (air adj		
		gap)) not (inductor and (oxide near1		
		layer) and (("low-k" dielectric) with (air		
		adj gap)))		
20	17	"6413827"	USPAT;	2004/09/07 08:19
			US-PGPUB;	
			EPO; JPO	Į l
21	0	6413827.pn. and inductor	USPAT;	2004/09/07 08:20
-	 	with allowood	US-PGPUB;	2004/05/07 08:20
22	О	"=C12765+n"	EPO; JPO	2004/00/05 00 00
44	ا ۲	"sc12765tp"	USPAT;	2004/09/07 09:30
			US-PGPUB;	İ
			EPO; JPO	

	,			
23	14	(low adj k adj dielectric) with	USPAT;	2004/09/07 09:37
		(semiconductor adj fabrication adj	US-PGPUB;	
24	0564763	process)	EPO; JPO	2004/00/07 00 20
24	8564763	US -6,486,061 B1	USPAT;	2004/09/07 09:38
}		US -6,472,325 B1	US-PGPUB;	
		US -6,465,372 B1	EPO; JPO	
		US -6,455,443 B1		
		US -6,440,878 B1		
		US -6,383,913 B1		
		US -6,348,407 B1		
		US -6,331,420 B1		
		US -6,303,525 B1		
		US -6,197,704 B1		
		US -6,153,512		
25	11	6486061.pn.	USPAT;	2004/09/07 09:47
		6472325.pn.	US-PGPUB;	
		6465372.pn.	EPO; JPO	
		6455443.pn.		
		6440878.pn.		
		6383913.pn.		
		6348407.pn.		
		6331420.pn.		
		6303525.pn.		
		6197704.pn.		
	_	6153512.pn.	****	
26	0	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/09/07 09:50
		adj k)) with void with polish\$3	US-PGPUB;	
			EPO; JPO	
27	1	(substrate wafer) with (low adj "k") with	USPAT;	2004/09/07 09:52
		void with polish\$3	US-PGPUB;	
	_		EPO; JPO	
28	1	(substrate wafer) with (low adj "k") with	USPAT;	2004/09/07 09:52
		(void (via adj hole)) with polish\$3	US-PGPUB;	
			EPO; JPO	
29	11		USPAT;	2004/09/07 10:10
		(void via hole) with polish\$3	US-PGPUB;	
			EPO; JPO	
30	8	```	USPAT;	2004/09/07 10:11
		(void via hole) with polish\$3) and cvd	US-PGPUB;	
			EPO; JPO	
31	8		USPAT;	2004/09/07 10:24
		with (void via hole) with polish\$3) and	US-PGPUB;	
		cvd) and cmp	EPO; JPO	
32	2	"5912187"	USPAT;	2004/09/07 10:24
			US-PGPUB;	
	_		EPO; JPO	
33	/	"6322714 <i>"</i>	USPAT;	2004/09/07 10:24
			US-PGPUB;	
34			EPO; JPO	0004/00/07
34	3	"6352934 <i>"</i>	USPAT;	2004/09/07 10:24
			US-PGPUB;	
35			EPO; JPO	0004/00/07 50 5:
35	6	"6399432"	USPAT;	2004/09/07 10:24
]		US-PGPUB;	
2.5			EPO; JPO	
36	4	"6458646"	USPAT;	2004/09/07 10:24
]			US-PGPUB;	
	_	/ DECT 04 04 05 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	EPO; JPO	
38	0	("5912187" "6322714" "6352934" "6399432"	USPAT;	2004/09/07 10:34
		"6458646") and ((local\$2 adj doped) with	US-PGPUB;	
3 =		undoped with etch\$3)	EPO; JPO	
37	20	"5912187" "6322714" "6352934" "6399432"	USPAT;	2004/09/07 10:39
		"6458646"	US-PGPUB;	
		4000400	EPO; JPO	
39	5	6399432.URPN.	USPAT	2004/09/07 10:42
40	15	("4373249" "5336355" "5438006"	USPAT	2004/09/07 10:43
		"5529197" "5629544" "5652172"		
		"5654570" "5677563" "5718800"		
1	I I	"5739066" "5789295" "5827747"		
		"5830789" "5831313" "5956584").PN.]